Hirata

Security code : 6258 November 2024

Financial Results Explanatory Materials

FY2024 (March 2025) Second quarter

Note : This document has been translated from the Japanese original for reference purposes only. In the event of any discrepancy between this translated document and the Japanese original, the original shall prevail.

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Hirata

Company Profile

Company Name	HIRATA Corporation
Address	111 Hitotsugi, Ueki, Kita, Kumamoto, 861-0198 Japan
Representatives	Yuichiro Hirata, President
Date Established	December 29, 1951
Capital	2,633 million yen
Our business	Manufacture and sales of various manufacturing line systems, Industrial robot and logistic equipment
Stock Exchange Listings	Tokyo Stock Exchange, Prime Market (Symbol:6258)
Employees	Consolidated 2,432 Non-Consolidated 1,535
Plants and office	7 bases in Japan(4 bases in Kumamoto 1 each in Tochigi, Shiga, Tokyo)
Subsidiaries	3 subsidiaries in Japan(2 in Kumamoto, 1 in Tokyo) 9 overseas subsidiaries(America、Mexico、Germany、Singapore、Thailand、 Malaysia、2 in China、Taiwan)

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I. FY2024 Second Quarter Results (Consolidated)

Financial Summary *Second Quarter Cumulative Period

- Order received We have received multiple large projects related to automobiles. In addition, the semiconductor industry has shown signs of recovery in the second quarter, resulting in an increase compared to the same period last year.
- Sales The production of the projects we have received orders for, mainly in the automotive sector, has progressed, resulting in an increase compared to the same period last year.
- Operating profit We have brought forward the recording of some expenses that were traditionally recorded in the fourth quarter. Additionally, the deterioration of the cost ratio for some projects in the first quarter has had an impact, resulting in a decrease compared to the same period last year.

(Units in millions of Yen)

	FY2023 2Q	FY2024 2Q	YoY Change	
	Actual results	Actual results	Amount of +/-	Percentage of +/-
Orders Received	42,724	43,975	1,250	2.9%
Net Sales	37,394	40,365	2,970	7.9%
Operating Profit (Profit ratio)	3,111 (8.3%)	2,765 (6.8%)	▲346	▲11.1%
Ordinary Profit	3,281	2,708	▲572	▲17.5%
Profit attributable to owners of parent	2,303	1,803	▲499	▲21.7%
Backlog of Orders	67,334	69,014	1,679	2.5%

Factor Analysis on Changing Operating Profit

• Operating profit decreased approximately 340 million yen from the same period of the previous year. -Main factors for increase : Increase in sales -Main factors for decrease : Increase in cost ratio and the selling and administrative expenses, etc. in some projects



Results by Segment

(Units in millions of Yen)		FY2023 2Q	FY2024 2Q	Amount of +/-	Percentage of +/-
	Total	42,724	43,975	1,250	2.9%
	Automobile	19,404	24,733	5,329	27.5%
Received	Semiconductor	13,838	13,393	▲444	▲3.2%
orders	Other Automatic Labor- saving Equipment	8,091	4,724	▲3,367	▲41.6%
	Others	1,390	1,123	▲266	▲19.2%
	Total	37,394	40,365	2,970	7.9%
	Automobile	16,585	18,895	2,309	13.9%
Net Sales	Semiconductor	13,431	14,174	742	5.5%
	Other Automatic Labor- saving Equipment	6,268	6,186	▲81	▲1.3%
	Others	1,109	1,109	0	0.0%
	Total	3,111	2,765	▲346	▲11.1%
	Automobile	1,014	1,298	284	28.0%
Operating	Semiconductor	2,240	1,801	▲438	▲19.6%
protit	Other Automatic Labor- saving Equipment	▲106	▲308	▲202	-
	Others(Including elimination)	▲36	▲26	9	-
	Total	67,334	69,014	1, 679	2.5%
Dealling (Automobile	34,460	44,988	10,528	30.6%
Backlog of	Semiconductor	22,160	18,689	▲3,470	▲15.7%
orders	Other Automatic Labor- saving Equipment	9,844	4,833	▲5,011	▲50.9%
	Others	869	502	▲366	▲42.2%

I.FY2024 Second Quarter Results (Consolidated)

Results by Segment : Automobile-related

- Received orders increased compared to the same period last year. Although a slowdown in growth is observed in the overall EV market, this is the result of receiving large orders for EV battery charge and discharge related equipment and EDU assembly lines.
- Sales increased compared to the same period last year. This is the result of progress in the production of EV-related projects (mainly EDU and battery-related) and internal combustion engine projects that were ordered in the previous term.
- The change in the timing of recognizing some expenses (from Q4 to Q2) lowered operating profit, but the increase in revenue outweighed this effect, leading to an increase in profit, with operating profit rising compared to the same period last year.

(Units in millions of Yen)

		FY202	3 2Q	FY202	4 2Q	YoY C	hange
		Results	Segment composition	Results	Segment composition	Amount of +/-	Percentage of +/-
Receiv	ed orders	19,404	-	24,733	-	5,329	27.5%
	EV	15,606	80.4%	18,690	75.6%	3,084	19.8%
	Others	3,797	19.6%	6,042	24.4%	2,245	59.1%
Net Sa	les	16,585	-	18,895	-	2,309	13.9%
	EV	12,869	77.6%	12,794	67.7%	▲74	▲0.6%
	Others	3,716	22.4%	6,100	32.3%	2,384	64.2%
Backlog	of orders	34,460	_	44,988	-	10,528	30.6%
Operatir	ng profit	1,014	-	1,298	-	284	28.0%
Operating	profit ratio	6.1%	-	6.9%	-	-	-
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I. FY2024 Second Quarter Results (Consolidated)

Results by Segment : Semiconductor-related

- Received orders are on par with the same period last year. Although orders other than wafer transport were below the same period last year, wafer transport-related orders showed a recovery trend in the second quarter.
- Sales increased compared to the same period last year. This is the result of progress in the production of wafer transport due to the increase in orders.
- Operating profit decreased compared to the same period last year. This is due to a reduction in some high-margin projects and the change in the timing of recognizing certain expenses (from Q4 to Q2) has led to a decrease in operating profit.

		FY202	3 2Q	FY202	4 2Q	YoY C	hange
		Results	Segment composition	Results	Segment composition	Amount of +/-	Percentage of +/-
Receive	ed orders	13,838	-	13,393	-	▲444	▲3.2%
	Wafer transfer	8,668	62.6%	11,046	82.5%	2,378	27.4%
	Others	5,169	37.4%	2,346	17.5%	▲2,823	▲54.6%
Net Sal	es	13,431	-	14,174	-	742	5.5%
	Wafer transfer	7,857	58.5%	9,871	69.6%	2,014	25.6%
	Others	5,574	41.5%	4,302	30.4%	▲1,271	▲22.8%
Backlog	of orders	22,160	-	18,689	-	▲3,470	▲15.7%
Operatin	g profit	2,240	-	1,801	-	▲438	▲19.6%
Operating p	profit ratio	16.7%	_	12.7%	-	-	-

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(Units in millions of Yen)

Hirata **Results by Segment : Other Automatic Labor-saving Equipment**

- Received orders decreased compared to the same period last year. It fell below the previous year's level, which had been supported by orders from the organic EL and home appliance sectors. This was also influenced by factors such as the postponement of customer capital investments.
- Sales were on par with the same period last year. Although production of ordered projects progressed, it resulted in sluggish performance due to factors such as customer investment delays.
- Operating profit decreased compared to the same period last year. This was influenced by the deterioration of the cost ratio in some projects, as well as the change in the timing of recognizing certain expenses (from Q4 to Q2) has led to a decrease in operating profit.

	FY2023 2Q		FY2024 2Q		YoY Change	
	Results	Segment composition	Results	Segment composition	Amount of +/-	Percentage of +/-
Received orders	8,091	_	4,724	-	▲3,367	▲ 41.6%
Net Sales	6,268	_	6,186	-	▲81	▲1.3%
Backlog of orders	9,844	_	4,833	-	▲5,011	▲50.9%
Operating profit	▲ 106	-	▲308	-	▲202	-
Operating profit ratio	▲1.7 %	-	▲5.0%	-	-	-

Balance Sheet

(Units in millions of Yen)

Assets	FY2023	FY2024 2Q	YoY change
Current Assets	88,554	85,556	▲2,997
Cash & deposits	10,652	8,456	▲2,196
Trade receivables, etc.	59,504	60,425	920
Inventories	14,264	14,484	219
Others	4,131	2,190	▲1,941
Tangible Assets	42,233	42,284	51
Tangible fixed assets	27,437	26,954	▲483
Intangible fixed assets	904	1,038	133
Investment & other assets	13,891	14,291	400
Total Assets	130,787	127,841	▲2,946

Liabilities	FY2023	FY2024 2Q	YoY change
Current liabilities	49,864	42,040	▲7,823
Fixed liabilities	15,621	18,723	3,102
Total Liabilities	65,485	60,764	▲ 4,721
Net Assets			
Total net assets	65,302	67,077	1,775

Main factors for increase/decrease

- Cash and deposits decreased as payments for factory expansion costs and accounts payable progressed.
- Current liabilities decreased due to the payments for factory expansion costs and bonuses, which led to a reduction in accounts payable and accrued expenses, as well as partial repayment of short-term borrowings.
- Fixed liabilities increased due to the rise in large projects and long-term projects, leading to an increase in long-term borrowings.



II. FY2024 Full Year Forecasts (Consolidated)

Full Year Forecast

• Sales are expected to increase to 100 billion yen, with operating profit projected to rise to 7.5 billion yen.

%The information remains unchanged from the fiscal year 2023 financial statement announcement on May 10, 2024.

(Units in millions of Yen)

	FY2023	FY2024	YoY Change	
	Results	Full year forecast	Amount of +/-	Percentage of +/-
Net Sales	82,839	100,000	17,160	20.7%
Automobile-related	36,984	50,000	13,015	35.2%
Semiconductor- related	27,390	29,000	1,609	5.9%
Other Automatic Labor- saving Equipment	16,083	19,000	2,916	18.1%
Others	2,381	2,000	∆381	∆16.0%
Operating Profit (x)	6,047 (7.3%)	7,500 (7.5%)	1,452	24.0%
Ordinary Profit (x)	6,259 (7.6%)	7,300 (7.3%)	1,040	16.6%
Profit attributable to owners of parent (x)	4,344 (5.2%)	4,700 (4.7%)	355	8.2%

II. FY2024 Full Year Forecasts (Consolidated) Key Points of Full Year Forecast (Operating Profit)

- We will actively implement investments in human resources and growth to achieve "profitability" enhancement" and "strengthening of management foundation" for the next phase of growth.
- We anticipate an increase in operating profit compared to the previous period.
- The information remains unchanged from the fiscal year 2023 financial statement announcement on May 10, 2024.



Personnel investment 710 million yen

- Increase in hiring to meet future demand
- Increase in personnel expenses to address the rapid increase in prices and ensure stable talent acquisition, etc.

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Growth investment 780 million ven

- · Accelerating the development of nextgeneration product in existing businesses
- Capital investment for improving productivity.

1.41 billion ven

- Increase in selling, general, and administrative expenses due to sales
- Increase in procurement cost, etc.

*The impact amount: increase/decrease for full year 2024 compared to full year 2023 results

Progress Status Against the Full year Forecast

• As of the end of the second quarter, the progress rate against the full year forecast is approximately 40% for sales and approximately 37% for operating profit.

	FY2023	FY2024 2Q	FY2024	(Units in millions of Yen)
	Results	Results	Full year forecast	Progress rate against the forecast
Net Sales	82,839	40,365	100,000	40.4%
Automobile- related	36,984	18,895	50,000	37.8%
Semiconductor -related	27,390	14,174	29,000	48.9%
Other Automatic Labor-saving Equipment	16,083	6,186	19,000	32.6%
Others	2,381	1,109	2,000	55.5%
Operating Profit (x)	6,047(7.3%)	2,765(6.8%)	7,500 (7.5%)	36.9%

- Although both sales and operating profit have been delayed in progress until the second quarter due to impacts such as customers postponing investments, there is an outlook to achieve the full year forecast through recovery in the second half.
- Although production load will increase in the second half, production capacity has improved due to capital investments and human resource investments during the period. External resources will also be utilized to address any shortfalls.
- In the second half, in addition to a high revenue growth effect, an improvement in profit margins is expected as the number of projects with high novelty and many development elements (which have high cost ratios) decreases.



III. Capital Policy

II. Capital Policy Transition and Forecast of Dividends and Dividend Ratio per Share

							(Units in Fen)
		FY2019	FY2020	FY2021	FY2022	FY2023	FY2024 forecast
Di Sł	vidends per nare	40.00	65.00	65.00	90.00	100.00	120.00
Di Ra	vidend atio (%)	23.8	16.6	25.2	21.9	23.9	26.5

Note: Dividend ratio is on a consolidated basis.

(1)

<Our approach to dividends>

We consider the return of profits to shareholders as one of the most important management challenges and strive to strengthen our financial position. Taking into account our consolidated performance and future business development, we aim for a consolidated dividend payout ratio of 20% or more as a general guideline, and we strive to provide stable and continuous dividends.

For the current fiscal year, we anticipate a year-end dividend of 120 yen.

Regarding our future approach to dividends, we will continue to consider it as part of our capital policy, which includes shareholder return strategies.

II. Capital Policy Acquisition of Treasury Shares

• To improve capital efficiency and respond to changes in the business environment, we will acquire treasury shares as part of our flexible capital policy.

Important matters	Contents
Type of shares to be acquired	Our common stock
Total number of shares that can be acquired	250,000 stocks(maximum) (Percentage of total number of shares issued (excluding treasury stock)2.4%)
Total acquisition cost of the shares	1 billion yen(maximum)
Acquisition period	From November 11, 2024 to March 31, 2025

(For reference) Status of treasury stock holdings as of September 30, 2024.

•Total number of issued shares 10,386,997 (excluding treasury shares)
•Number of treasury shares 369,093





*We changed our business classifications effective from FY2022.

IV. Reference Data ⁽²⁾ Quarterly Trends by Business Segment [Received Orders]



IV. Reference Data 3 Quarterly Trends by Business Segment [Net Sales]



IV. Reference Data @ Hirata Quarterly Trends by Business Segment [Operating Profit]

*Others includes elimination



IV. Reference Data (5)

R&D, CAPEX, Depreciation and Amortization



IV. Reference Data (6) **Production space (Non-consolidated ·End of period)**

- We are actively working on the continuous expansion of production space to increase our production capacity.
- We will secure additional production space in Yamaga City, which is adjacent to Kumamoto City, for the fiscal year 2024 as well.



IV. Reference Data ⁽²⁾ Number of recruits · employees (Non-consolidated ·End of period)

- In anticipation of business expansion, we are committed to ensuring a continuous supply of talented professionals.
- We are working on talent retention through various measures such as wage improvements, workstyle reforms, enhancing employee benefits, and providing quality education and training opportunities.



Potential opportunities/risks from the main external environment and countermeasures

Assumed main external environment	Assumed opportunities / risks	Main countermeasures
Exchange rate (depreciation of the yen)	Oppor tunity• Relative increase in price competitiveness against overseas competitorsRisk• Increase in the effective purchase price of overseas procured goods	 Aggressive expansion of orders for overseas projects Promotion of local production overseas
U.S. presidential election	Risk • Refraining from investment due to concerns about EV market trends	 Understanding investment trends through close information exchange with customers Securing new customers and projects by expanding the scope of services Diversification of core business and optimization of resource allocation
Mass-production of new type batteries	Oppor tunityExpanding business opportunities through the pursuit of new technologies and the ability to mass-productionRiskDeterioration in profitability due to the burden of development factors	 Participating from the research and development stage of our customers and developing and proposing that meet their requirements Reducing R&D expenses through external sourcing/procurement
Proliferation of generative AI	Oppor tunityIncrease in demand related to semiconductor related businessRiskMissing orders due to lack of production capacity and human resources	 Improvement of QCD to obtain continuous inquiries from existing customers Resource investment in semiconductor field Pre-investment in human resources and production capacity in anticipation of an expansion in orders
Concentration of semiconductor-related industries in Kumamoto and Kyushu	Oppor tunity Risk Increase in demand related to semiconductor related business Intensification of competition for talent acquisition	 Improvement of QCD to obtain continuous inquiries from existing customers Resource investment in semiconductor field = Pre-investment in human resources and production capacity in anticipation of an expansion in orders Recruiting new talent actively Implementing wage revisions and retention measures taking into account societal trends

The list of large-scale purchase order projects we disclosed starting from FY2023 and onwards

Business segment	Disclosu	re date	Outline of the equipment	Amount
	2023	June	EDU assembly equipment for EVs	More than 8 billion yen
Automobile -related	2024	January	Battery charging and discharging related equipment for EVs	More than 4 billion yen
		February	Engine assembly equipment for internal combustion engines	Approximately 13 billion yen
		May	Battery charging and discharging related equipment for EVs	Approximately 2.5 billion yen
		August	Battery charging and discharging related equipment for EVs	Approximately 5.6 billion yen
		August	EDU assembly equipment for EVs	Approximately 8.7 billion yen

- The cumulative order amount of battery charging and discharging related equipment since the fiscal year 2022 has exceeded 15 billion yen.
- Our ability to handle large-scale projects and the track record of delivering battery charging and discharging related equipment for EVs have been highly evaluated, leading to continuous order acquisition.

IV. Reference Data ⁽¹⁾ Strengthening our efforts in ESG management

2022	Oct.	Human Rights Policy is formulated and Procurement Basic Policy is revised.		
2023	Apr.	The Sustainability Promotion Committee is established.		
		Sustainability page is established in our web page and the dissemination of ESG information is been strengthened.		
	Sep.	We signed the UN Global Compact.		
	Oct.	Human rights due diligence is implemented.		
	Nov.	We express our support for the Keidanren's "Corporate Code of Conduct."		
2024	Jan.	Code of Conduct of the Hirata Group is established.		
		Human Rights Respect Working Group within the Sustainability Promotion Committee is established.		
	Jun.	Hirata has been selected as a constituent stock for the followings: [FTSE Blossom Japan Index] [FTSE Blossom Japan Sector Relative Index]		

Hirata Business Overview : Main products of automobile-related business

 Continued orders from North American automakers (big three). North American emerging EV manufacturers, domestic electronic components manufacturers, focusing on EV related

Main/Expansion Fields of EV-related business

Production equipment handled by Hirata



*Completed product image



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EDU assembly equipment Main field

Manufacturing EV-drive parts assembly equipment called EDU (ELECTRIC DRIVE UNIT) combined with in-vehicle motors and gearboxes



2 IGBT·Inverter assembly equipment Main field

Manufacturing of in-vehicle electronic components mounted on EVs and transmissions such as IGBT and inverters.

Battery-related assembly equipment Expansion field



(Cell charging / discharge process)

Manufacturing of conveying equipment for charging and discharging processes that are part of the battery cell progress.

Main customers, competitors, superiority

EDU	assembly
equi	pment

North America

Customers North American automakers (Big Three)

 North American emerging EV manufacturers

equipment	Battery-related assembly equipment (cell charging/discharging process	
Japan	apan	
Customers	C ustomers	
Domestic electronic	Domestic battery	
components manufacturers	nanufacturers	

Hirata's superiority

- Ability to handle large facilities, some of which exceed 1 km in total length, solely in-house
- A vast factory that allows us to build the customer's production line in our factory and install it on site after verifying the production capacity and quality
- Integrated system from development to production and maintenance
- Engineering ability to respond to customer requests

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Hirata Business Overview : Charging and discharging related equipment

- We have charge and discharge equipment that handles the final process of cell manufacturing, which is the "charging and discharging" process.
- We have a competitive advantage in systematization utilizing conveyance and stocking technologies.

Battery manufacturing process



Hirata Business Overview : Main products of semiconductor-related business

 Continuing orders mainly for wafer transport devices for domestic device manufacturers and handling devices between inspection devices

Main/Expansion Fields of Semiconductor-related business



Main customers, competitors, superiority

Wafer transport	Transport device between	PLP	Hirata's superiority
device Japan Customers Domestic manufacturing equipment manufacturers	inspection device North America, Japan Customers • North American device makers • Domestic inspection equipment manufacturers	North America, Europe, Japan Customers • North American device makers • Domestic/European substrate manufacturers	 A wealth of component line Knowledge technology requortmization to meet custor Integrated system from deviation technology
			 Engineering ability to response

- au
- uired for customization and mer requirements
- velopment to production and
- ond to customer requests

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IV. Reference Data (4)

Business Overview : Wafer transport device

• Manufacturing of load ports that take wafers into various processing equipment mainly used in the front-end process of semiconductor manufacturing, wafer transfer robots that transfer wafers, and EFEMs that integrate them

Semiconductor manufacturing process Process in which our PLP is primarily used

Design	Front-end process	Back-end process
 Design for circuit and pattern Photomask creation 	 Wafer creation Circuit pattern creation Oxidation of wafer surface Thin film formation Pattern transcription of photomask Ion implantation 	 Dicing Die bonding Wire bonding Packaging Commercialization and final inspection

Image of our product installation



Multiple EFEM/load ports are used on a single line because EFEM/load ports are installed at each processing unit.

Our main products



%FOUP : It is a container for wafers that holds multiple wafers and

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IV. Reference Data (5)

Business Overview : PLP

 Designing and manufacturing conveyance equipment used in PLP, an advanced packaging technology that is expected to expand

Semiconductor		Difference of packaging process			
manufacturin	ng process	Process in which our PLP is primarily used	Conventional packaging	Circuits are formed of chips into smaller pie bonded and encapsu complete the produc	on wafters, and after cutting the eces, they are individually Ilated onto substrates to ct.
 Design for circuit and pattern Photomask creation 	 Wafer creation Circuit pattern creation Oxidation of wafer surface 	Dicing Die bonding Wire bonding Packaging	WLP (Wafer Level Package)	After cutting the chi chips are rearranged are bonded and enca while the chips are s cut individually.	ps individually, only the good d on the wafer, and then they apsulated onto the substrate till on the wafer. They are then
	 Thin film formation Pattern transcription of photomask Ion implantation 	Commercialization and final inspection	PLP (Panel Level Package)	After cutting the chips individually, only the good chips are rearranged on a square-shaped panel, and then they are bonded and encapsulated onto the substrate while the chips are still on the panel. They are then cut individually.	
What is PLP • The packaging proc have been individua square-shaped subs This is a packaging	(Panel Level Packa ess involves rearranging ally cut after circuit form strates and then collecti technology called "PLP".	aging) about? numerous chips that ation onto thin, vely molding them.	The chips that have been rearranged.	300mm	Panel
 In PLP, panel substrates larger than the standard 300mm wafer size, such as 510x515mm square, are commonly used. 			200mm	50011111	600×600 mm

• The panel substrate uses printed circuit boards, glass substrates for LCD panel manufacturing, and copper plates.

WLP

PIP

Hirata **Business Overview : Other Automatic Labor-saving Equipment**

 Manufacturing products for various industrial fields such as organic EL vapor equipment, assembly equipment for home appliances, and medical physics and chemical equipment

Main/New Fields of Other Automatic Labor-saving Equipment

Main field

Medical physiology and chemical equipment

Manufacturing a system for sample tests (pathological tissue specimen device and fully automatic continuous thinning device)

Assembly equipment for home appliances

Manufacturing all equipment, including motor assembly equipment built into high-performance home appliances

Organic EL Vapor Equipment

Contracted the manufacturing of vacuum vapor equipment for organic EL panels

• • • • • • • • • • • • • • • • • • •	
New field for monetization	 Focused ultrasound therapy equipment for Pancreatic Cancer Under Development with SONIRE Therapeutics Inc. (Headquarters: Shinjuku-ku, Tokyo, SONIRE, hereinafter, Sonia)
Focused ultrasound therapy equipment	 Aiming for non-invasive cancer treatment that fuses SONIRE's Ultrasonic Technology with our robot technology Started clinical trials in a person and started developing the next mass production device

Main customers, competitors, superiority

Medical physiology and chemical equipment	Assembly equipment for home appliances	Organic EL Vapor equipment	 Hirata's superiority Extensive knowledge and expertise in production
Japan Customers Domestic medical specialty manufacturers	Asia Customers Asian home appliance manufacturers	Japan Customers Domestic manufacturing device manufacturers	 Tacilities and equipment in various fields Integrated system from development to production and maintenance Engineering ability to respond to customer requests

Business Overview : High-Intensity Focused Ultrasound (HIFU) cancer treatment device

• Hirata is applying its experience in specimen examination automation and robotics technology in the medical and scientific equipment field to enter the "treatment" domain.



- Partnership with SONIRE Therapeutics Inc. (SONIRE) in the medical and scientific equipment field
- Joint development of a cancer treatment device for clinical trials (targeting inoperable pancreatic cancer)
- Development of a device for minimally invasive treatment that does not involve skin incisions or organ removal
- Supplied to multiple domestic hospitals, and currently conducting domestic clinical trials at SONIRE. Hirata is providing after-sales service post-delivery
- In the future, we aim to refine the device's safety, usability, and design, and work towards the development of massproduced devices and the establishment of a mass production system.
- We are planning to expand overseas, aiming for early delivery to overseas hospitals and after-sales service at our overseas locations.

Please be aware that the performance forecasts and future predictions mentioned in this document are based on the information available to us at the time of its creation. They are subject to potential risks and uncertainties, such as changes in economic conditions, competition with other companies, and exchange rates. Therefore, please note that actual performance may significantly differ from the future outlook mentioned or described in this document due to various factors, including changes in the business environment.